

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Chi Keung LEE et al) Group Art Unit: Unassigned
Application No.: Unassigned) Examiner: Unassigned
Filed: January 15, 2002)
For: A METHOD OF FORMING A)
DUAL-INTERFACE IC CARD AND)
A CARD FORMED OF SUCH A)
METHOD)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination and the calculation of filing fees, kindly amend the above-identified application as follows.

IN THE CLAIMS:

3. (Amended) A method according to Claim 1 wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.
4. (Amended) A method according to Claim 1 further including a step (f) of positioning a first part of said integrated circuit within said first cavity.

7. (Amended) A method according to Claim 5 wherein said second cavity is narrower than said first cavity.

8. (Amended) A method according to Claim 1 including a step (h) of applying an adhesive material on at least part of said first cavity.

9. (Amended) A method according to Claim 1 further including a step (i) of removing an insulating coating from said end(s) of said antenna coil.

Add the following new claims:

12. (New) A method according to Claim 2 wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.

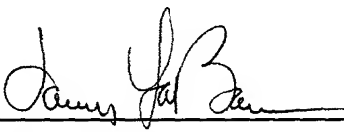
13. (New) A method according to Claim 6 wherein said second cavity is narrower than said first cavity.

REMARKS

Entry of the foregoing amendments is respectfully requested. These amendments are intended to eliminate the multiple dependency of the claims.

Respectfully submitted,

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Attachment to Preliminary Amendment dated January 15, 2002

Marked-up Claims 3, 4, 7-9

3. (Amended) A method according to Claim 1 [or 2] wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.

4. (Amended) A method according to [any of the preceding claims] Claim 1 further including a step (f) of positioning a first part of said integrated circuit within said first cavity.

7. (Amended) A method according to Claim 5 [or 6] wherein said second cavity is narrower than said first cavity.

8. (Amended) A method according to [any of the preceding claims] Claim 1 including a step (h) of applying an adhesive material on at least part of said first cavity.

9. (Amended) A method according to [any of the preceding claims] Claim 1 further including a step (i) of removing an insulating coating from said end(s) of said antenna coil.